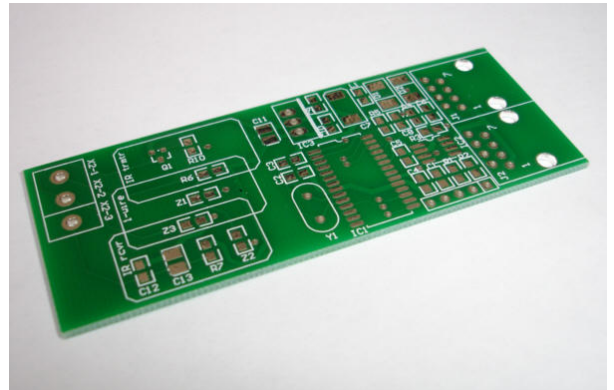


Printed Circuit Board and Enclosure

for temperature sensor application UNIV 1.0.4.0 (CPU)

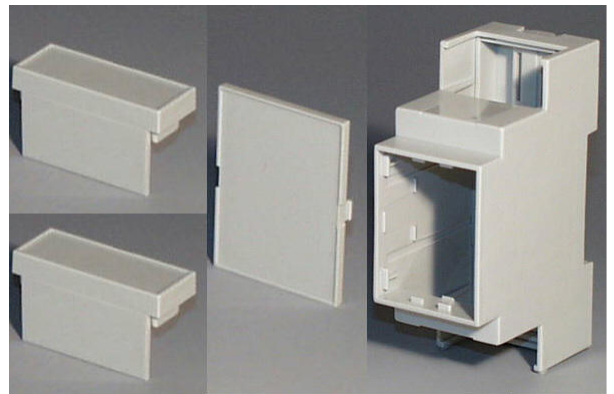
Printed Circuit Board:

- Printed circuit board for applications with use of processor UNIV 1.0 (CPU)
 - infrared receiver UNIV 1.0.3.0
 - temperature sensor UNIV 1.0.4.0
 - infrared transmitter UNIV 1.0.5.0
- PCB dimensions: 86mm x 33mm



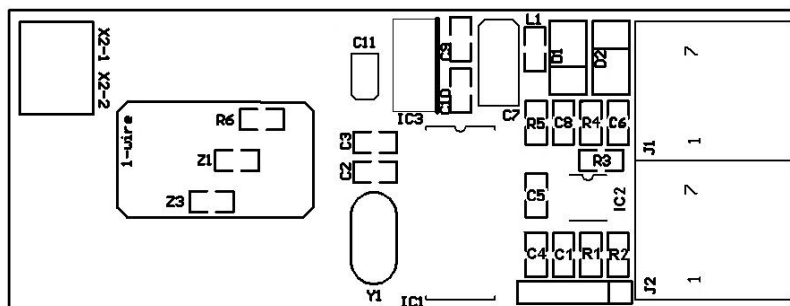
Enclosure:

- 2 module wide 35mm DIN rail enclosure
- Enclosure dimensions: 90mm x 58mm x 36mm

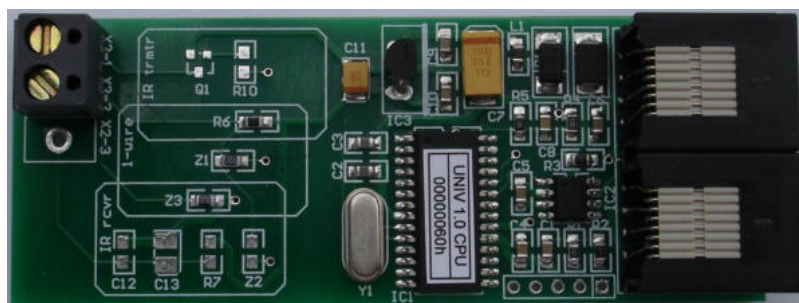


1. Printed Circuit Board

1.1. Assembly schematic

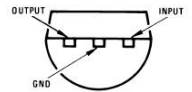


1.2. Assembled PCB



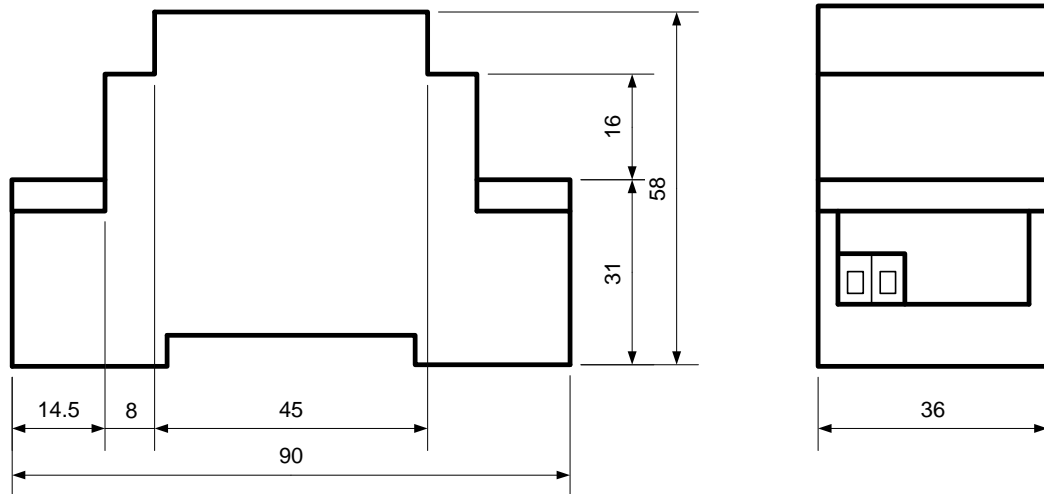
1.3. Components

Designator	Type	Footprint	Description
C1, C4, C5, C6, C8, C9, C10	0.1uF	0805	Capacitor
C2, C3	22pF	0805	Capacitor
C7	10uF/35V	SME	Electrolytic Capacitor
C11	10uF/16V	SMB	Electrolytic Capacitor
R1	10k	0805	Resistor
R2	470 Ohm	0805	Resistor
R3	4k7	0805	Resistor
R4	51k 1%	0805	Resistor
R5	10k 1%	0805	Resistor
R6	2k5	0805	Resistor
Z1, Z3	0 Ohm	0805	Resistor
L1	BLM21A102SPT	0805	Choke
Y1	4MHz	HC49-S	Quartz crystal
D1	FS1J	DO-214	Diode
D2	P6SMB33CA	DO-214	Transil diode
IC1	UNIV 1.0 (CPU)	SOIC-28	Processor of HAPCAN universal module
IC2	MCP2551-SN	SOIC-8	CAN Transceiver
IC3	LM7805L	TO-92	Voltage regulator
J1	RJ45	L18xW15xH11	Connector
J2	RJ45	L18xW15xH11	Connector
X2	ARK2	H=12,5mm raster=5mm	Terminal block



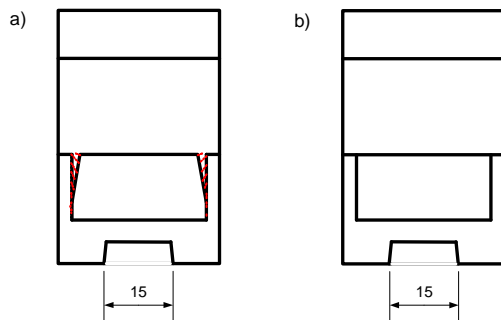
2. Enclosure

2.1. Dimensions



2.2. Mechanical processing

2.2.1. Main part

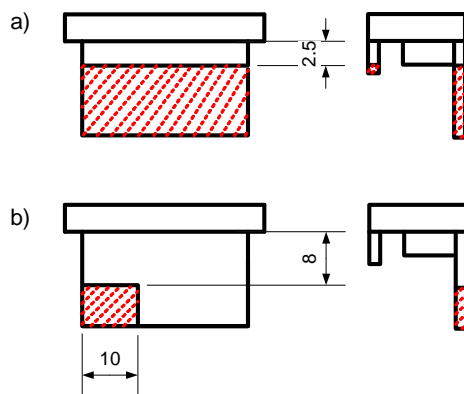


A view from the side, where shown detail is 15mm wide.

Drawing a) shows striped part which must be cut out.

Drawing b) is a view when striped parts have been cut out.

2.2.2. Terminal guards



Striped parts must be removed.

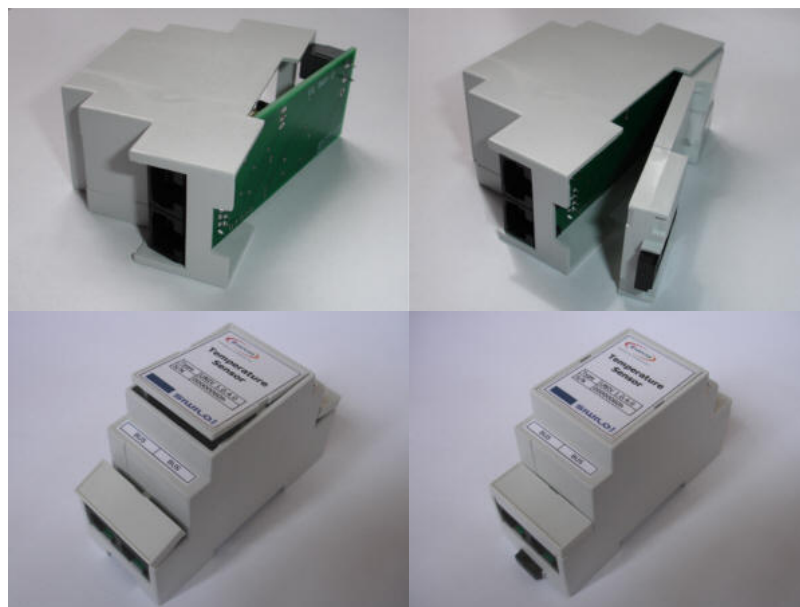
Drawing a) shows RJ45 connector guard.

Drawing b) shows terminal block guard.

2.2.3. Front panel

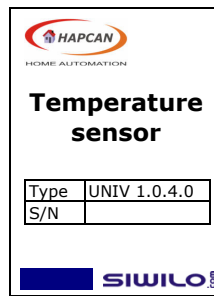
Does not need processing.

2.3. Assembling



2.4. Labels

GND 1wire



BUS	BUS
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3. Document version

File	Description	Date
univ_v1-0-4-0-pcba.pdf	Original version	June 2008